



Name : .....  
Roll No. : .....  
Invigilator's Signature : .....

**CS/B.Tech(ECE/NEW)/SEM-7/EC-702/2009-10  
2009**

**EDA FOR VLSI DESIGN**

Time Allotted : 3 Hours

Full Marks : 70

*The figures in the margin indicate full marks.*

*Candidates are required to give their answers in their own words as far as practicable.*

**GROUP – A**

**( Multiple Choice Type Questions )**

1. Choose the correct alternatives for any *ten* of the following :  
10 × 1 = 10

- i) The example of physical defects is
  - a) oxide defects
  - b) resistive shorts and opens
  - c) slower transition
  - d) none of these.
- ii) The example of electrical faults is
  - a) slower transition
  - b) logical stuck-at-0 or stuck-at-1
  - c) bridging faults
  - d) none of these.
- iii) LUT is used in
  - a) CPLD
  - b) ASIC
  - c) FPGA
  - d) SPLD.



- iv) What is the full form of VHDL ?
  - a) Very high speed digital logic
  - b) Verilog hardware description language
  - c) Very high digital logic
  - d) None of these.
- v) In a PLA
  - a) only AND array is programmable
  - b) only OR array is programmable
  - c) both OR & AND array are programmable
  - d) macro cell is the building block.
- vi) The graph that is used to represent an algorithm is known as
  - a) a signal flow graph    b) a data flow graph
  - c) a control flow graph    d) a binary decision graph.
- vii) High level synthesis has design constraints like
  - a) Area                      b) Timing
  - c) Power                     d) All of these.
- viii) VHDL is a
  - a) multi threaded program
  - b) a programming language like C
  - c) single user program
  - d) sequential program.
- ix) The suitable interconnect among the following is
  - a) Aluminium              b) Gold
  - c) Copper                    d) Silver.
- x) Minimum transistor gates required to design XOR gate is
  - a) six                         b) eight
  - c) twelve                    d) ten.



- xi) VLSI design flow is a  
 a) cyclic process only  
 b) parallel process  
 c) sequential and cyclic process  
 d) none of these.
- xii) In VHDL, sequential statements are defined in the  
 a) architecture                      b) process  
 c) package                              d) none of these.
- xiii) Which of the following logical operator does not follow associative properties ?  
 a) OR                                      b) XOR  
 c) NAND                                  d) AND.
- xiv) In full custom ASIC design  
 a) All the diffused layers are defined  
 b) All the lithographic layers are defined  
 c) All the metal layers are defined  
 d) None of these.
- xv) Which of the following is not a part of FPGA ?  
 a) RTL                                      b) I/O  
 c) PI                                         d) CLB.

**GROUP – B**

**( Short Answer Type Questions )**

Answer any *three* of the following.                      3 × 5 = 15

2. a) What is ASIC ? Give its classification.                      2  
 b) Why VLSI design flow is often called as cycle ? Explain.                      3
3. What are the steps in VLSI design flow ? Explain.
4. a) What do you mean by testability of a circuit ?  
 b) Describe the method of Built-In Self Test Technique.                      1 + 4
5. What is PLA ? Derive a PLA programming table for the combinational circuit that squares a 3 bit number.                      1 + 4
6. What is an FPGA ? How is it different from CPLD ? What are its advantages ?                      1 + 2 + 2



**GROUP – C**

**( Long Answer Type Questions )**

Answer any *three* of the following.  $3 \times 15 = 45$

7. a) What are the issues that a hardware description language must address ? Explain briefly. 5
- b) Describe the purpose of the following : 5
  - i) the entity declaration
  - ii) the architecture body.
- c) Write the VHDL code for HALF ADDER circuit. 5
8. a) Why FPGA is preferred over CPLD ? Explain the architecture of FPGA. 4
- b) Write the steps for programming a FPGA. 4
- c) How Look Up Table ( LUT ) is used to program an FPGA ? Explain with an example. 7
9. a) What are the characteristics of any material to be used as interconnect ? 5
- b) What are problems associated with aluminum interconnect ? 5
- c) "Placement is a fundamental problem in physical design". Explain with an example and necessary diagrams. 5
10. a) How the logic capability of PLA measured ? 3
- b) What are the differences between PAL and PLA ? 2
- c) Implement the following functions using PLA : 5
  - i)  $f = AB' + A'B$
  - ii)  $f = A + ( B + C ). D$
- d) Explain the architecture of PLD. 5
11. Write short notes on any *three* of the following : 3 × 5
  - a) Scan Based Techniques
  - b) Built-In-Self Test ( BIST ) techniques
  - c) XILINX FPGA architecture
  - d) Analog design automation tools
  - e) NORA logic.